

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A method of manufacturing a plasma display device having a panel in which a pair of substrates having transparency at least on a front side, the substrates being oppositely disposed so that a discharge space and discharge cells are formed between the substrates, and—a metallic holding plate that supports the panel via a thermal conductive material, and a driving circuit block containing a semiconductor device for feeding a display signal to the panel, the method comprising:

forming the thermal conductive material of a pull-to-remove type adhesive;

applying the adhesive to one of the panel and the holding plate, and applying heat and pressure to the panel and the holding plate for forming a bulging-out portion of the adhesive bulging out from between the panel and the plate;

curing the adhesive for bonding the panel and the holding plate together;

forming a groove around the holding plate for a portion of the adhesive to flow into the groove so that the portion of the adhesive can be prevented from hanging out outside the holding plate;

wherein the bulging-out portion is formed by bulging out from a part of the holding plate, and the part does not have the groove the driving circuit block is in contact with the bulging out portion bulging out from between the panel and the holding plate.

2. - 12. (Cancelled)

13. (Currently Amended) The method of manufacturing the plasma display device of Claim 1, wherein a—the driving circuit block containing—a semiconductor device for feeding—a display signal to—the panel—is mounted on a cooling plate on a back side of the holding plate, a portion of the thermal conductive material is exposed from the holding plate, and the driving

circuit block-mounted cooling plate is bonded with the exposed portion of the thermal conductive material.

14. (Currently Amended) The method of manufacturing the plasma display device of Claim 1, wherein ~~a-the driving circuit block containing a semiconductor device for feeding a display signal to the panel~~ is mounted on a cooling plate on a back side of the holding plate, a portion of the thermal conductive material is extended to the driving circuit block-mounted cooling plate.

15. - 18. (Cancelled)

19. (Previously Presented) The method of manufacturing the plasma display device of Claim 1, further comprising pulling the bulging-out portion to allow the panel to be removed from the holding plate.

20. (New) The method according to claim 1, wherein heat and pressure are used to cure the adhesive.